

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/11/2022

Details for "TPS717185DSER"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS717185DSER	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DSE   6	1.5x1.5x0.75	3.4

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.013841	97.664409	976644	0.404232	4042
Precious Metals	Palladium	7440-05-3	0.000331	2.335591	23356	0.009667	97
Sub-Total			<b>0.014172</b>	<b>100</b>	<b>1000000</b>	<b>0.413899</b>	<b>4139</b>
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.021111	30	300000	0.616555	6166
Other Inorganic Materials	Silica	7631-86-9	0.003167	4.500497	45005	0.092493	925
Thermoplastics	Epoxy	85954-11-6	0.046092	65.499503	654995	1.346135	13461
Sub-Total			<b>0.07037</b>	<b>100</b>	<b>1000000</b>	<b>2.055183</b>	<b>20552</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	0.876994	97.443778	974438	25.612948	256129
Copper and Its Alloys	Iron	7439-89-6	0.021145	2.349444	23494	0.617548	6175
Copper and Its Alloys	Phosphorus	7723-14-0	0.000739	0.082111	821	0.021583	216
Zinc and Its Alloys	Zinc	7440-66-6	0.001122	0.124667	1247	0.032768	328
Sub-Total			<b>0.9</b>	<b>100</b>	<b>1000000</b>	<b>26.284847</b>	<b>262848</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.00973	97.3	973000	0.284168	2842
Precious Metals	Gold	7440-57-5	0.00003	0.3	3000	0.000876	9
Precious Metals	Palladium	7440-05-3	0.00021	2.1	21000	0.006133	61
Precious Metals	Silver	7440-22-4	0.00003	0.3	3000	0.000876	9
Sub-Total			<b>0.01</b>	<b>100</b>	<b>1000000</b>	<b>0.292054</b>	<b>2921</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	1.786231	90.499996	905000	52.167565	521676
Other Plastics and Rubber	Carbon Black	1333-86-4	0.009869	0.500016	5000	0.288228	2882
Thermoplastics	Epoxy	85954-11-6	0.177636	8.999988	90000	5.187928	51879
Sub-Total			<b>1.973736</b>	<b>100</b>	<b>1000000</b>	<b>57.643721</b>	<b>576437</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.455748	100	1000000	13.310296	133103
Sub-Total			<b>0.455748</b>	<b>100</b>	<b>1000000</b>	<b>13.310296</b>	<b>133103</b>
<b>Total</b>			<b>3.424026</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/eoinfo](http://www.ti.com/eoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.